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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



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Debbie Prout

Applicant : Rong-Fuh Shyu  
Application No. : 09/383,150  
Filed : August 25, 1999  
Title : LEAD FRAME FOR A  
SEMICONDUCTOR CHIP PACKAGE,  
SEMI CONDUCTOR CHIP PACKAGE  
INCORPORATING MULTIPLE  
INTEGRATED CIRCUIT CHIPS,  
AND METHOD OF  
FABRICATING...  
Grp./Div. : 2826  
Examiner : F. Abraham  
Docket No. : 35761/DBP/S295

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RESPONSE RE ELECTION OF CLAIM GROUP

Assistant Commissioner for Patents  
Washington, D.C. 20231

Post Office Box 7068  
Pasadena, CA 91109-7068  
December 26, 2000

Commissioner:

This is in response to the Official office action dated November 30, 2000.

Applicant hereby elects Claim Group I, claims 1-8, drawn to a packaging of a device.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By   
D. Bruce Prout  
Reg. No. 20,958  
626/795-9900

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